

SMACD 2026

JUNE 29th - JULY 2nd
DRESDEN, GERMANY

CALL FOR PAPERS

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The 2026 edition of the International Conference on Synthesis, Modeling, Analysis and Simulation Methods, and Applications to Circuit Design (SMACD) will be held from June 29th to July 2nd in Dresden, GERMANY. SMACD is a forum devoted to modeling, simulation, and synthesis for Analog, Mixed-signal, RF (AMS/RF), and multi-domain (nanoelectronics, biological, MEMS, optoelectronics, etc.) integrated circuits and systems, as well as, emerging technologies and applications. Open-source tools and methods for IC design and experiences with modeling, simulation, and synthesis techniques including system/technology co-optimization in diverse application areas are also welcomed. Objective technologies include CMOS, beyond CMOS, and More-than-Moore such as MEMs, power devices, sensors, passives, etc. **Accepted papers will be submitted for inclusion into IEEE Xplore® subject to meeting IEEE Xplore's scope and quality requirements.**

CAD AND EDA METHODS AND TOOLS FOR AMS SYSTEMS

Synthesis, Sizing & Optimization

- Multi-level Synthesis Methods
- Physical Synthesis Methods
- High-frequency Circuits & Systems
- Low-Power & Energy-aware Design
- Parasitic-aware Design
- Variability-aware & Reliability-aware
- Procedural Design Methods
- Sizing & Optimization Methods

Modeling

- Performance/Behavioral
- Power and Electro-thermal
- Reliability and Variability
- RF/microwave/mm-wave
- Signal/Power Integrity
- Electromagnetic Theory
- Transmission Line Theory
- Automated Model Generation
- Modeling of Chiplet-based Systems and Components

Simulation, Verification & Test

- Behavioral Simulation
- Numerical & Symbolic
- RF Circuit Simulation
- Electromagnetic Simulation
- Multilevel Simulation
- Analysis of Variability Effects
- Formal/Functional Verification
- Test & Design-for-Test

EMERGING TECHNOLOGIES AND APPLICATIONS (ETA)

CAD for Emerging Technologies

- CAD for Bio-Electronic Devices, Bio-Sensors
- CAD for Multi-Domain Devices and Circuits
- CAD using Cloud Computing
- AMS Soft and Hard IP Block Generation

ML for CAD/EDA

- ML for Device/Circuit Modelling
- ML for Circuit/System Simulation
- ML for Automatic Sizing and Layout

Hardware Security

- Hardware Security primitives (Methods, PUFs, etc.)
- Attacks and Counter-measures
- Anticounterfeiting
- Architectures and Tools for Secure Design

EMERGING DEVICES AND PARADIGMS

- Devices, Hardware and Methods for Bio-Inspired and Neuromorphic Computing

- Design Strategies using Emerging Devices

- Emerging Device Modeling
- Emerging Devices in Security

AMS ICS AND MULTI-DOMAIN DESIGN APPLICATIONS

- Internet of Everything
- Automotive Systems
- Biomedical and Bio-inspired CAS

- Low-Power Low Voltage CAS
- Sensors and Sensing Systems
- Security Systems

- Aerospace Systems
- Renewable Energy Systems

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IMPORTANT DATES

Final Extended Paper Submission Deadline March 27th, 2026
Author Notification April 28th, 2026
Camera Ready Paper Submission May 20th, 2026
Early Registration Deadline May 20th, 2026

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